

**Amendments to the Claims:**

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A process for powder coating, comprising applying a powder to a conductive surface or to a layer on said surface to form a coating on said surface or layer, wherein the powder has a geometric size distribution of about 1.10 to about 1.25 and is formed by aggregating and coalescing particles in an aqueous dispersion, said particles including resin particles.
2. (Original) The process of claim 1, wherein the powder is heated to melt the powder onto the conductive surface or layer, thereby forming said coating.
3. (Original) The process of claim 1, wherein the powder is cured to form said coating.
4. (Original) The process of claim 1, wherein said conductive surface is a metallic surface.
5. (Previously Presented) The process of claim 1, wherein said powder has a volume average diameter of less than or equal to about 30 microns.
6. (Previously Presented) The process of claim 5, wherein said powder has a volume average diameter of about 3 to about 20 microns.
7. (Original) The process of claim 1, wherein during said aggregating said resin particles are aggregated with colorant to form powder particles comprising at least one resin and at least one colorant.
8. (Original) The process of claim 7, wherein said at least one colorant is at least one pigment.

9. (Original) The process of claim 1, wherein during said aggregating said resin particles are aggregated with at least one of fillers and leveling agents to form powder particles comprising at least one resin and at least one of fillers and leveling agents.

10. (Previously Presented) The process of claim 1, wherein the resin particles comprise at least one resin selected from the group consisting of epoxy resins, polyester resins, acrylic resins, polyamide resins, polyolefin resins, plasticized polyvinyl chloride, polyester and poly (vinylidene fluoride), and ionomers, and copolymers and mixtures thereof.

11. (Original) The process of claim 1, wherein the resin particles comprise at least one curable resin.

12. (Original) The process of claim 11, wherein said powder further comprises at least one curing agent,

said process further comprising activating the curing agent to initiate curing of said powder, and allowing said powder to cure.

13. (Currently Amended) A process for powder coating, comprising:

a) forming powder having a geometric size distribution of about 1.10 to about 1.25 by:

i) aggregating, in an aqueous dispersion, particles including at least resin particles to form aggregated particles;

ii) coalescing said aggregated particles to form fused particles; and

iii) removing said fused particles from said aqueous dispersion to form said powder; and

b) applying said powder to a conductive surface or to a layer on said surface to form a coating on said surface or layer.

14-21. (Canceled)

22. (Previously Presented) The process of claim 1, wherein the resin particles comprise at least one thermoset resin.
23. (Previously Presented) The process of claim 1, wherein the resin particles comprise at least one thermoplastic resin.
24. (Previously Presented) The process of claim 1, wherein the resin particles have a volume average diameter from about 5 to about 500 nm and wherein the resin particles compose about 5 to about 40 percent by weight of the aqueous dispersion.
25. (Previously Presented) The process of claim 1, wherein during said aggregating said resin particles are aggregated with at least one additive to form powder particles.
26. (Previously Presented) The process of claim 25, wherein the at least one additive is selected from the group consisting of magnetites, flocculates, charge additives, flow-promoting agents, flow-control agents, plasticizers, stabilizers, anti-gassing and degassing agents, antioxidants, UV absorbers, light stabilizers, waxes and mixtures thereof.
27. (Previously Presented) The process of claim 13, wherein, after removing said fused particles from said aqueous dispersion, said fused particles are dry-blended with at least one additional additive to form said powder.
28. (Previously Presented) The process of claim 27, wherein, the at least one additional additive is selected from the group consisting of surface additives, fluidity assisting additives, flow-promoting agents, flow-control agents, curing agents, fillers, charge additives and mixtures thereof.
29. (Previously Presented) The process of claim 1, wherein the powder contains resin in an amount of from about 50 to about 100 percent by weight and the powder contains colorant in an amount of from about 1 to about 20 percent by weight

30. (Previously Presented) The process of claim 1, wherein the aggregating is accomplished at a temperature below the glass transition temperature of the resin particles.

31. (Previously Presented) The process of claim 1, wherein the aggregating is accomplished at a temperature of from about 25°C to about 60°C.

32. (Previously Presented) The process of claim 1, wherein the aggregating is accomplished at a temperature of from about 1°C to about 25°C below the glass transition temperature of the resin particles.

33. (Previously Presented) The process of claim 1, wherein the coalescing is accomplished at a temperature above the glass transition temperature of the resin particles.

34. (Previously Presented) The process of claim 1, wherein the coalescing is accomplished at a temperature of from about 70°C to about 120°C.

35. (Previously Presented) The process of claim 1, wherein the coalescing is accomplished at a temperature in the range from about 5°C to about 50°C above the glass transition temperature of the resin particles.

36. (Canceled)

37. (Currently Amended) A process, comprising applying a powder having a geometric size distribution of about 1.10 to about 1.25 over a conductive surface, wherein the powder is formed by aggregating and coalescing particles in an aqueous dispersion.

38. (Previously Presented) The process of claim 37, wherein the powder is heated to melt the powder onto the conductive surface, thereby forming a coating on the conductive surface.

39. (Previously Presented) The process of claim 37, wherein the particles comprise styrene-acrylate resin.

40. (Previously Presented) The process of claim 37, wherein the particles comprise at least one colorant selected from the group consisting of cyan colorants, magenta colorants and yellow colorants.